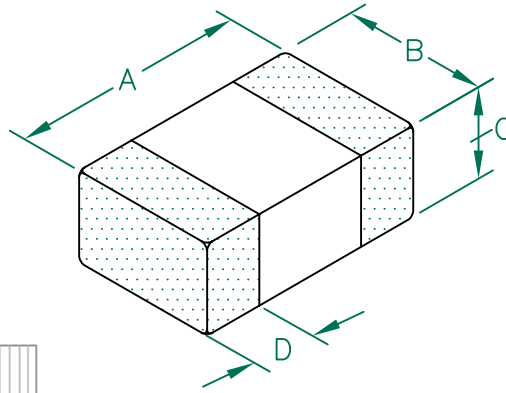


CPI0805H1R0R-10

UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:

A	2.00 [.079]	+ 0.20[.008]
B	1.25 [.049]	+ 0.20[.008]
C	0.90 [.035]	+ 0.10[.004]
D	0.50 [.020]	+ 0.20[.008]



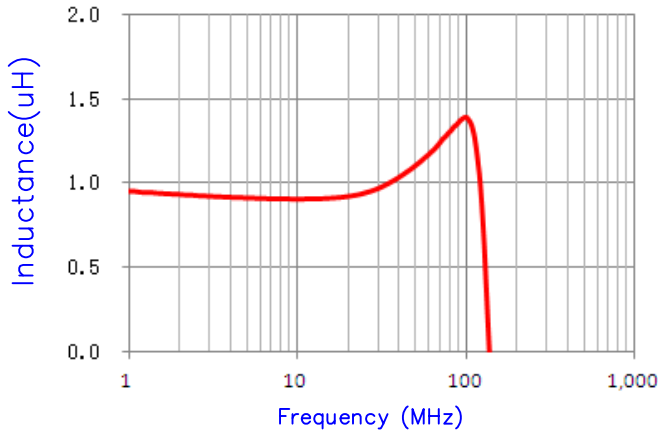
ELECTRICAL CHARACTERISTICS:

	L (μ H) @ 1MHz $\pm 20\%$	DCR (Ω) $\pm 25\%$	I (Max)
Nom	1.0	0.16	
Min	0.8	0.12	
Max	1.2	0.20	800mA

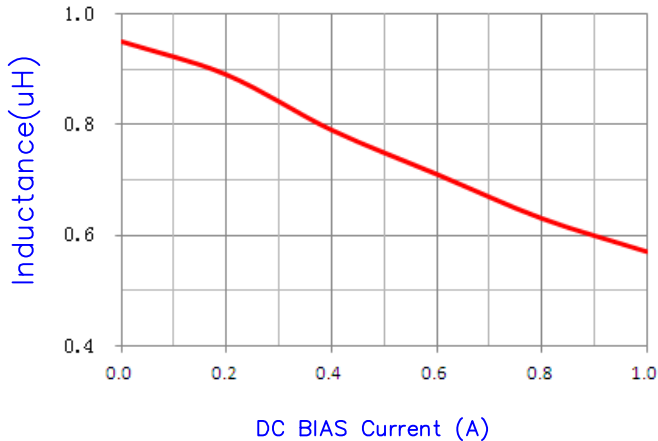
NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
5. OPERATION TEMPERATURE TEMP: -55°C~+125°C. (INCLUDING SELF-HEATING)

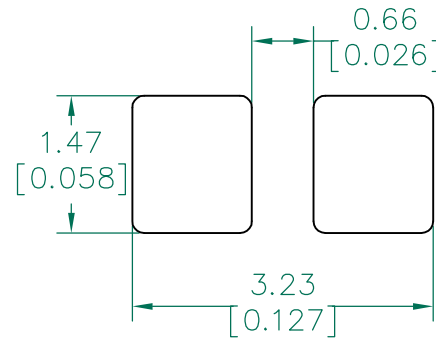
Ls vs Frequency



Ls vs DC BIAS Current

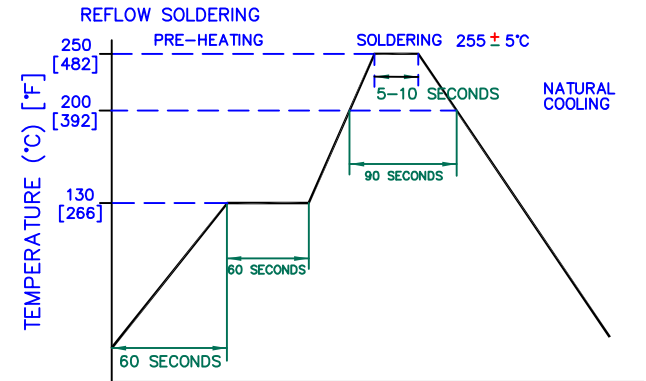


LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [0.030] to this dimension)

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
PROJECT/PART NUMBER:				REV			
C CHANGE PLASTIC TAPE TO PAPER TAPE 04/17/14 QU				C CO-FIRE QU			
B UPDATE LAIRD LOGO AND NOTES 5 08/05/13 QU				DRAWN BY: QU			
A ORIGINAL DRAFT 03/01/11 QU				DATE: 03/01/11			
REV DESCRIPTION DATE INT				SCALE: NTS SHEET: 1 of 1			
				TOOL # -			
				CPI0805H1R0R-10-A			

